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(54) **INTEGRATED AUDIO JACK HOUSING**

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H01R 24/58 (2011.01)
H01R 43/26 (2006.01)

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See application file for complete search history.

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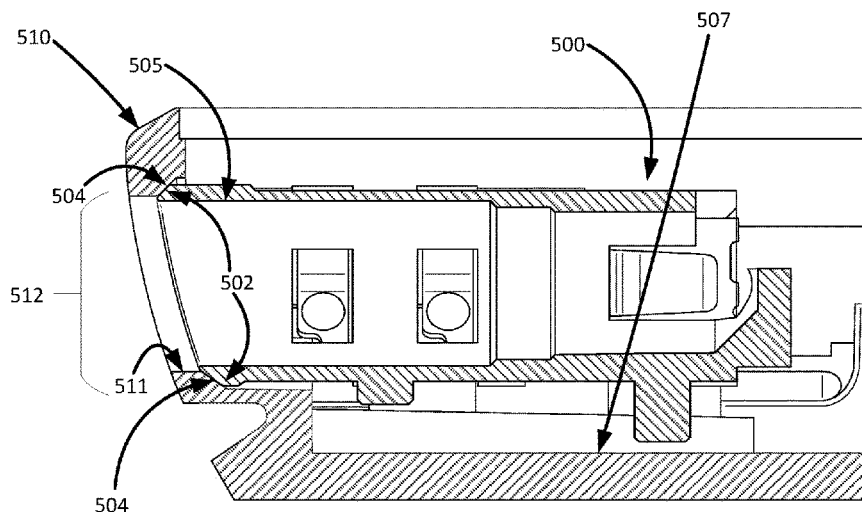
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(57) **ABSTRACT**

Technologies are described for an audio jack housing con-
centrically align with an opening in a chassis
of a computing device and to accept a plug associated with
external audio components. When the housing is aligned
with the opening, a snout of the audio jack housing abuts an
interior surface of the opening and does not protrude into the
opening. The chassis where the opening is located may be
constructed from a plastic material to reduce a risk of
shorting-out when a metal plug is inserted into the housing.
The chassis may include alignment features to concentri-
cally align the audio jack housing with the opening during
assembly, such that interior edges of the opening and interior
edges of the snout are flush creating a smooth interior entry
into the audio jack housing through the opening and the
snout.

19 Claims, 9 Drawing Sheets



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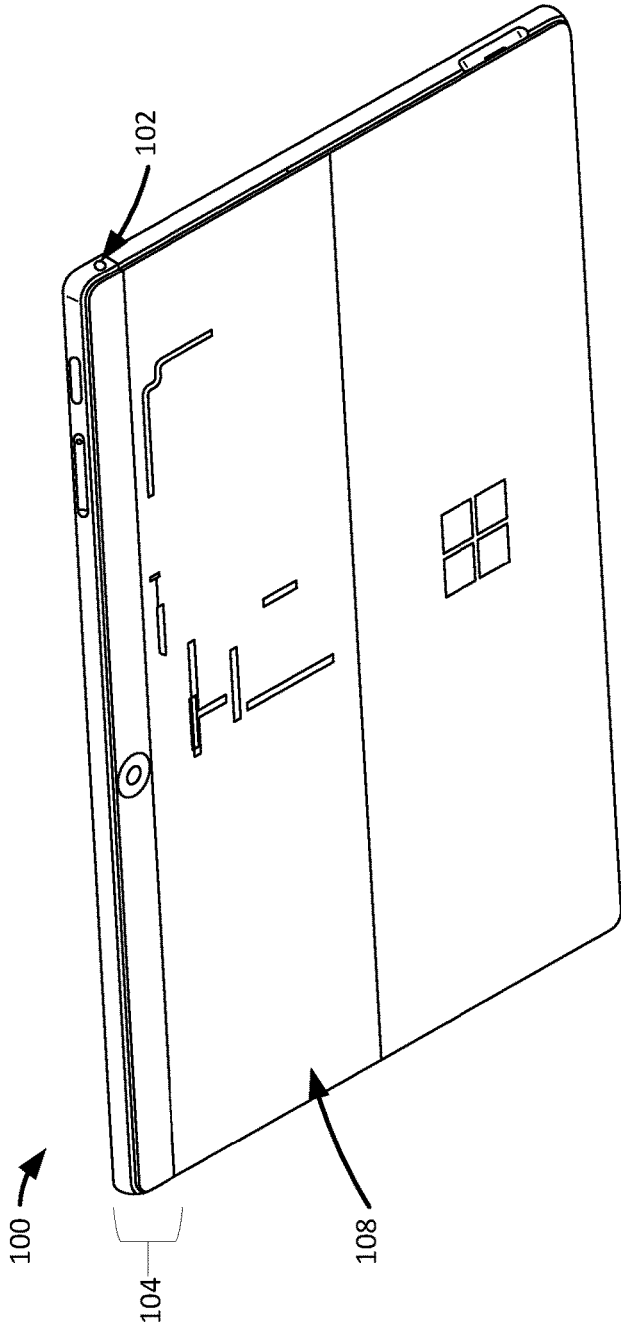


FIG. 1A

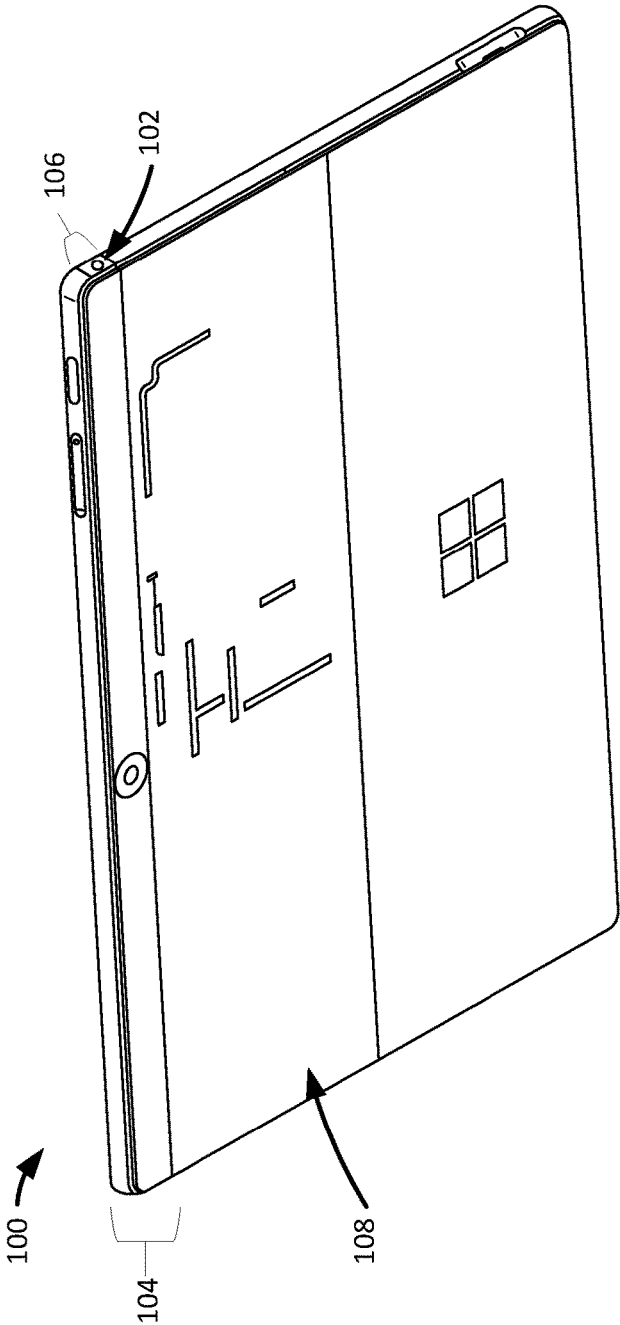


FIG. 1B

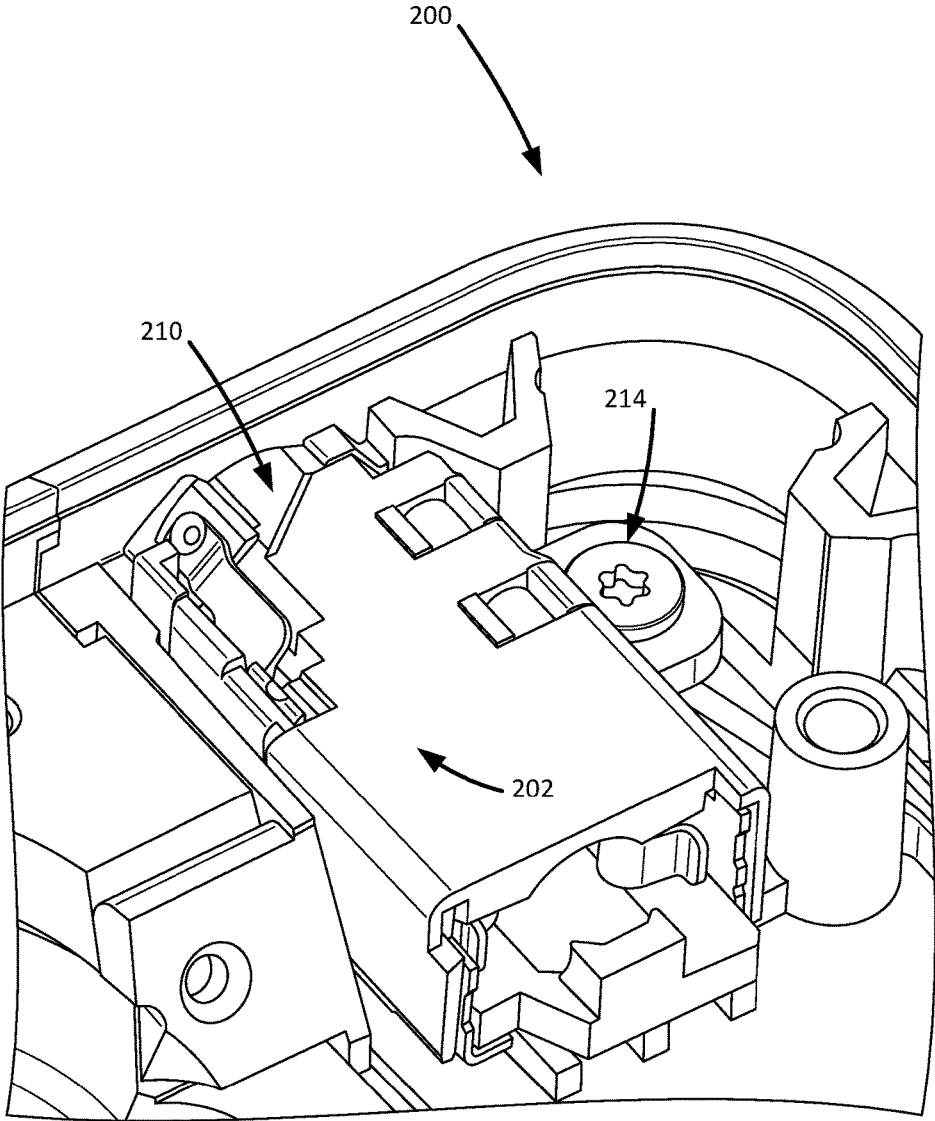


FIG. 2A

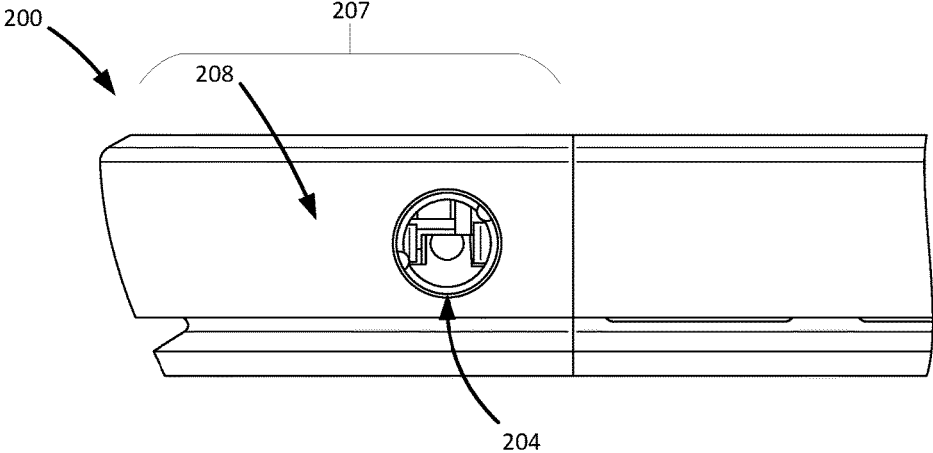


FIG. 2B

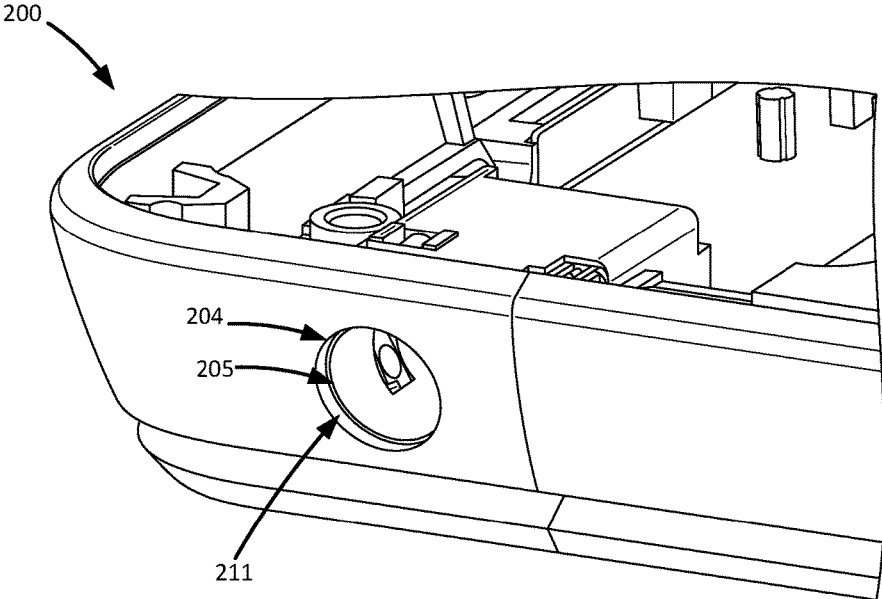


FIG. 2C

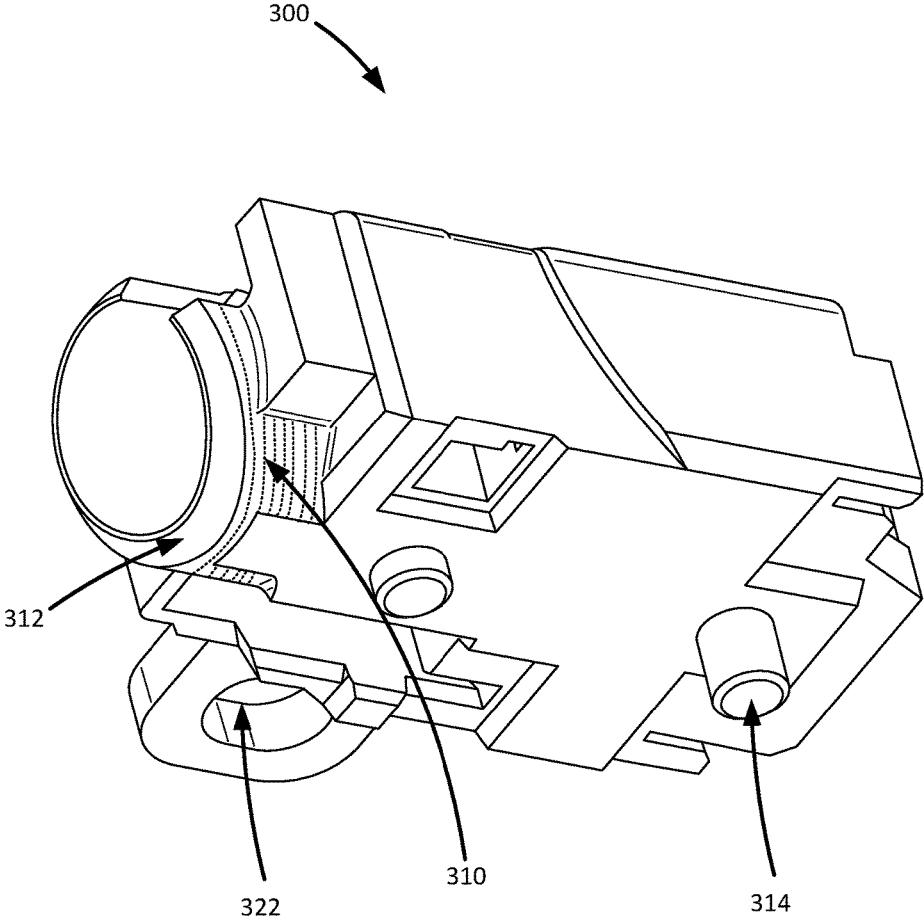


FIG. 3A

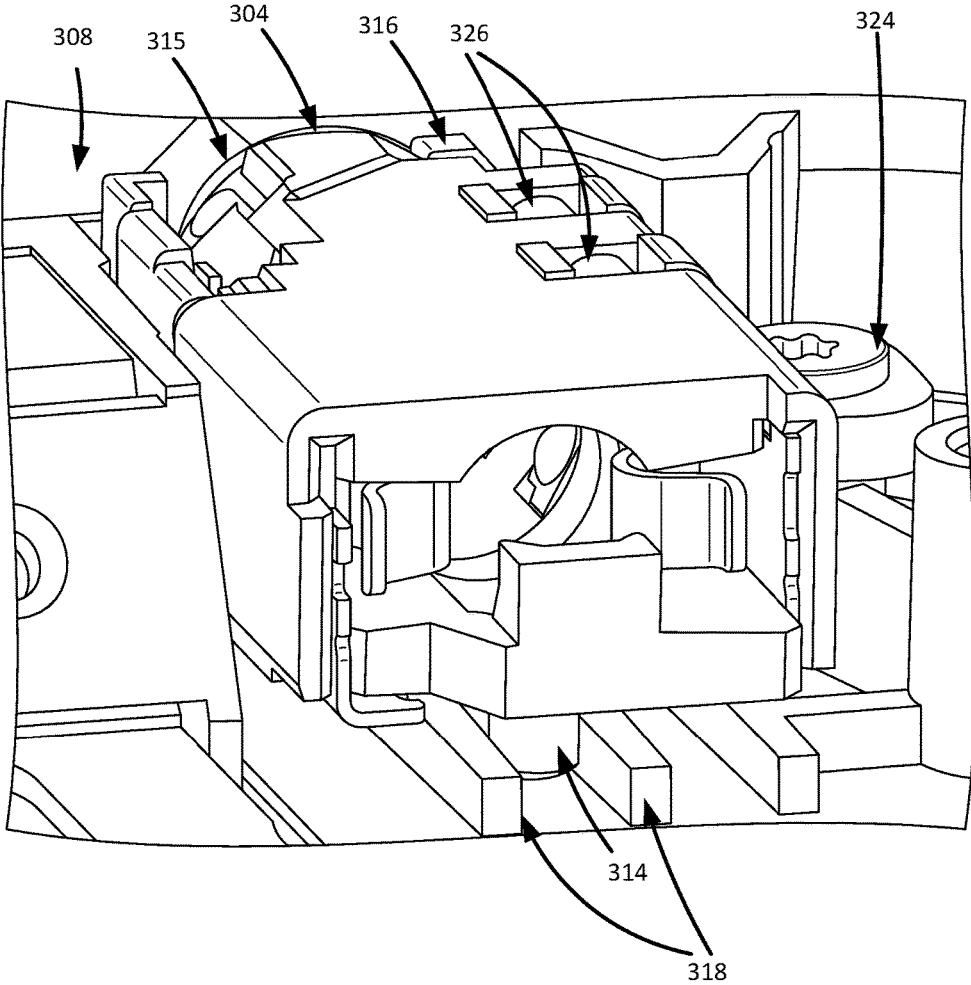


FIG. 3B

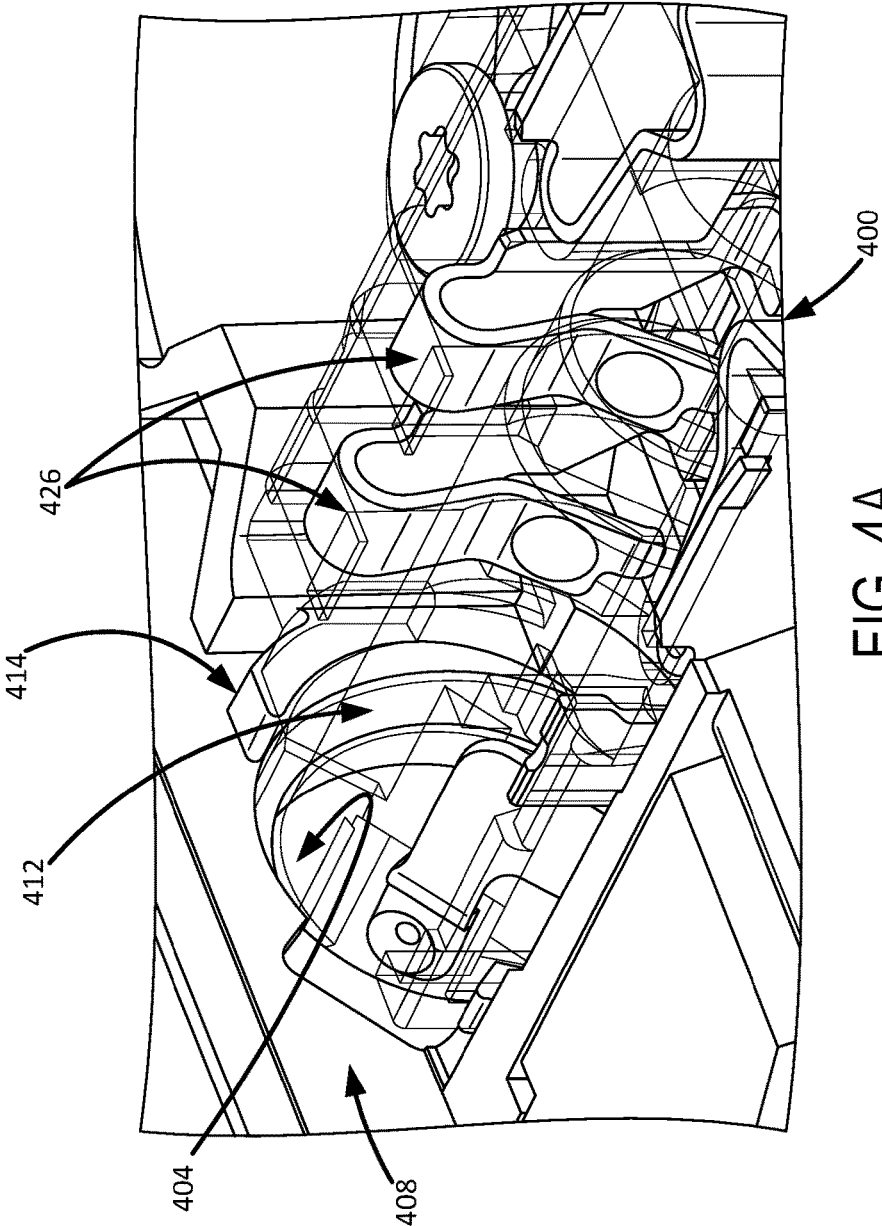


FIG. 4A

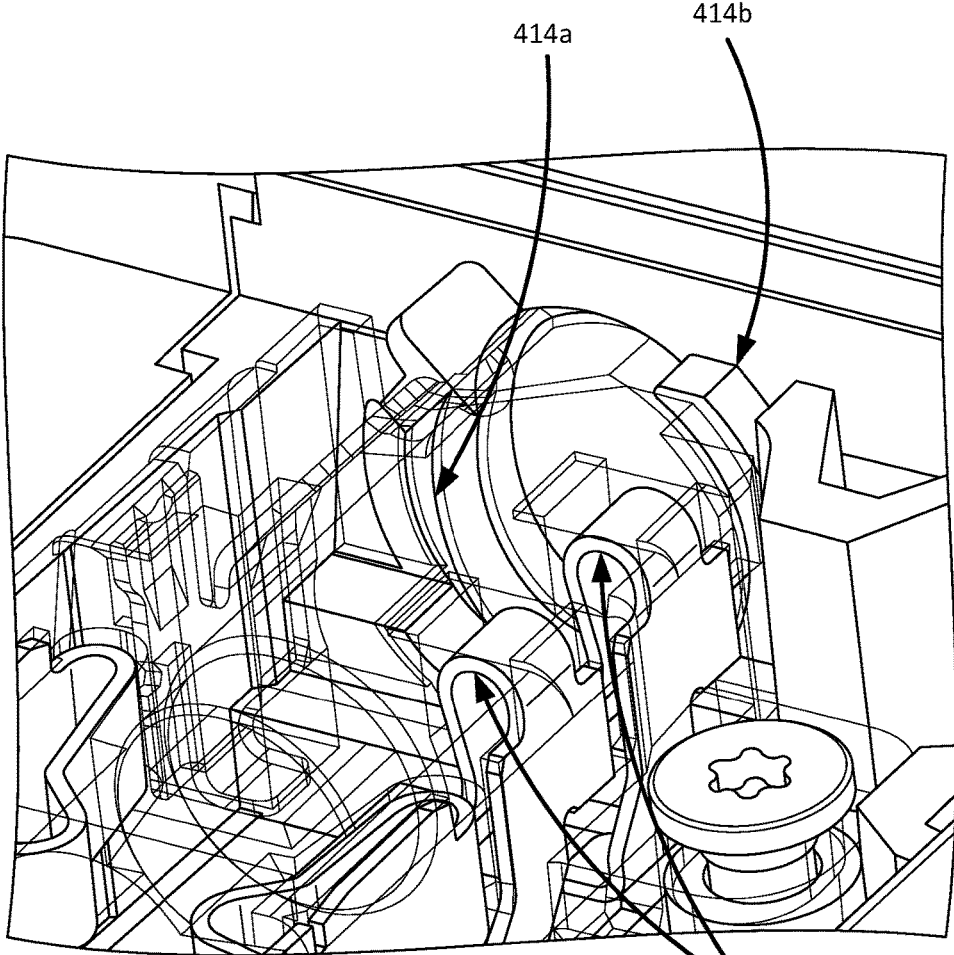


FIG. 4B

426

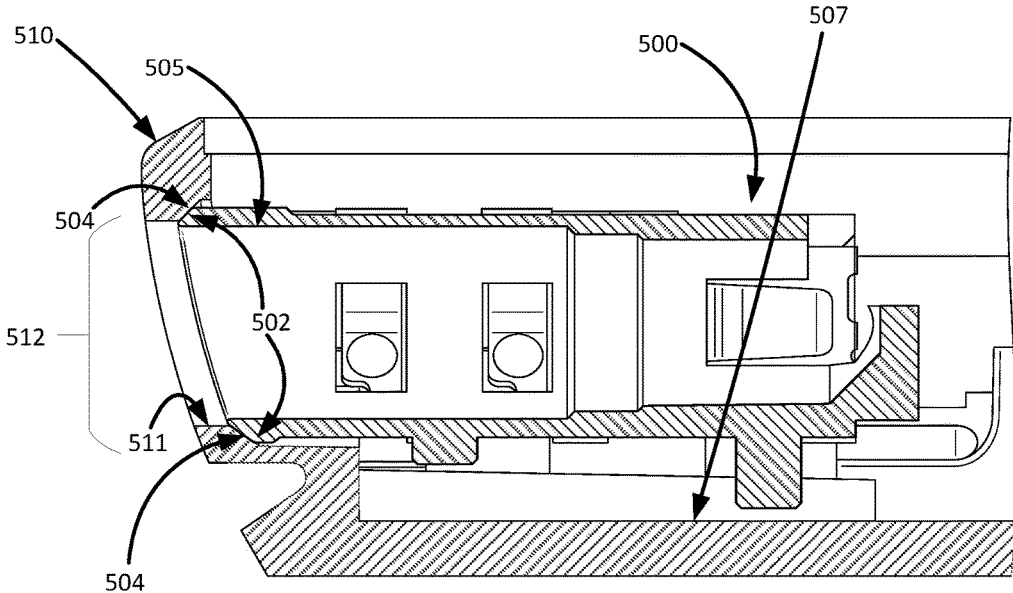


FIG. 5A

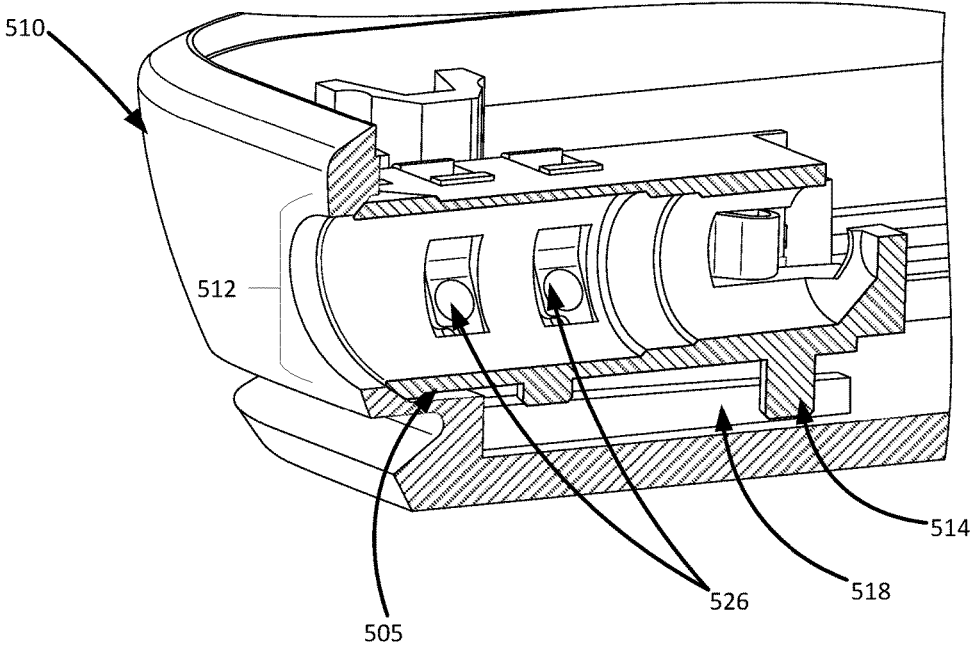


FIG. 5B

INTEGRATED AUDIO JACK HOUSING

BACKGROUND

Many computing devices, such as laptops, tablets, and mobile phones, and consoles, as well as single purpose audio players include audio jacks to enable connection to external components for inputting or outputting an audio source. These external components can include external speakers, headphones, microphones, and musical instruments. An external component connects to the computing device or audio player via an audio plug that inserts into the audio jack of the computing device or audio player.

Often, the audio jack is generally accessible through an opening, or socket, in the casing, or housing, of the device. However, the housing of devices is often formed of conductive material. Since many audio plugs are also formed of conductive material, contact between the metal plug and the metal audio jack opening may cause a short. In order to avoid creating the short, insulative material is used to isolate the two conductive parts. In some cases, an additional concentric insulation ring is inserted within the audio jack opening to line the opening and buffer the plug from contacting the conductive housing. However, the concentric insulation ring may be difficult to accurately align with the audio jack opening, resulting in an area for defects during the manufacturing processes due, for example, to a gap between the concentric insulation ring and the audio jack opening or other misalignment faults.

SUMMARY

The following summary is provided to introduce a selection of concepts in a simplified form that are further described below in the detailed description. This summary is not intended to identify key features or essential features of the claimed subject matter, nor is it intended to be used to limit the scope of the claimed subject matter.

Technologies are described for an audio jack housing configured to concentrically align with an opening formed in a chassis of a computing device and configured to accept insertion of a plug associated with external audio components. When the audio jack housing is in position and aligned with the opening in the chassis, a snout of the audio jack housing abuts an internal surface of the chassis around the opening and does not protrude into the opening. That is, the snout does not protrude past an interior edge of the opening. The chassis of the computing device where the opening is located may be constructed from a plastic material to reduce a risk of shorting out when a metal plug is inserted into the audio jack housing. An inner support surface of the chassis may include alignment features to concentrically align the audio jack housing with the opening during assembly, such that interior edges of the opening and the edges of the snout are flush creating a smooth entry into the audio jack housing through the opening and the snout.

These and other features and advantages will be apparent from a reading of the following detailed description and a review of the appended drawings. It is to be understood that the foregoing summary, the following detailed description and the appended drawings are explanatory only and are not restrictive of various aspects as claimed.

BRIEF DESCRIPTION OF THE DRAWINGS

FIGS. 1A-1B illustrate perspective views of some implementations of an example device that includes an integrated audio jack housing.

FIGS. 2A-2C illustrate partial exterior and interior views of chassis of a device with integrated audio jack housing according to an example implementation.

FIGS. 3A-3B illustrates an example audio jack housing.

FIGS. 4A-4B illustrate one or more alignment features for aligning an audio jack housing with an opening in a chassis according to an example implementation.

FIGS. 5A-5B illustrate cross sectional views of an audio jack housing in position and aligned with an opening in a chassis according to an example implementation.

DETAILED DESCRIPTION

The detailed description provided below in connection with the appended drawings is intended as a description of examples and is not intended to represent the only forms in which the present examples may be constructed or utilized. The description sets forth functions of the examples and sequences of steps for constructing and operating the examples. However, the same or equivalent functions and sequences may be accomplished by different examples.

References to “one implementation,” “an implementation,” “one example,” “an example” and the like, indicate that the described implementation or example may include a particular feature, structure or characteristic, but every implementation or example may not necessarily include the particular feature, structure or characteristic. Moreover, such phrases are not necessarily referring to the same implementation or example. Further, when a particular feature, structure or characteristic is described in connection with an implementation or example, it is to be appreciated that such feature, structure or characteristic may be implemented in connection with other implementations or examples whether or not explicitly described.

Numerous specific details are set forth in order to provide a thorough understanding of one or more aspects of the described subject matter. It is to be appreciated, however, that such aspects may be practiced without these specific details. While certain components are shown in block diagram form to describe one or more aspects, it is to be understood that functionality performed by a single component may be performed by multiple components. Similarly, a single component may be configured to perform functionality described as being performed by multiple components.

Various aspects of the subject disclosure are now described in more detail with reference to the drawings, wherein like numerals generally refer to like or corresponding elements throughout. The drawings and detailed description are not intended to limit the claimed subject matter to the particular form described. Rather, the intention is to cover all modifications, equivalents and alternatives falling within the scope of the claimed subject matter.

FIGS. 1A-1B illustrate perspective views of some implementations of an example device that includes an integrated audio jack housing.

In this example, computing device **100** may be a computing device such as a tablet, mobile device, or a notebook that includes an opening **102** for insertion of an audio plug associated with an external audio device. The computing device **100** (e.g. the computing device) may include a display screen, such as a touch sensitive display screen. The computing device can also include computing elements such as processor, memory/storage, a battery, and/or a video or graphics processor, among other components/elements. The computing device **100** may also be a laptop or a personal computer that also includes a second portion secured to the computing device **100** such as a keyboard.

In some examples an external portion of the computing device **100** may be constructed from various materials for various functional and/or cosmetic reasons. For purposes of this Specification, the housing or structural framework of the computing device may be referred to as a “chassis.” That is, the chassis may include a surrounding frame or housing and also an internal supporting structure, or an inner support surface, on which circuit boards and other internal parts and electronics of a computing device may be mounted.

In some implementations, the chassis **108** of the computing device **100** may be primarily constructed from a metal material, such as a magnesium alloy. As shown in FIGS. **1A** and **1B**, a combination of different materials may be used to construct the chassis **108** of computing device **100**. For example, at least a portion of the computing device **100** chassis **108** may be composed from a plastic material for functional reasons, such as for antenna radiation. In the example computing device **100** shown in FIG. **1A**, a portion **104** of the chassis **108** may be composed from a plastic material to enable antenna radiation. A size of the plastic portion **104** may vary based on antenna needs of the computing device **100**. Other materials may also be contemplated for construction of the chassis **108**. For example, other composite materials may be chosen for functional and/or cosmetic considerations.

In other examples, a portion of the computing device **100** chassis **108** may be composed from a plastic material for other functional reasons, such as to enable insertion of an audio plug within the opening **102** of the computing device **100** without causing a risk of shorting out the device. That is, in computing devices where an audio plug, which may often be a metal or other conductive material, is inserted into the opening **102** in the outer surrounding frame of the chassis **108** that is also composed from a metal material, there may be a risk that contact between the metal audio plug and the metal opening in the chassis **108** may cause the computing device to short out. Therefore, as shown in FIGS. **1A** and **1B** described in further detail below, the opening **102** may be formed in a portion of the surrounding frame of the chassis **108** that is composed from a plastic material, or another composite material that will not cause shorting out when a metal audio plug comes into contact with the opening **102**. For example, in computing devices where a portion of the surrounding frame of the chassis **108** is composed from plastic for functional reasons, such as for antenna radiation, the opening **102** may be formed in the plastic portion of the surrounding frame of the chassis **108** where the antennae are located as shown in FIG. **1A**.

In other examples, as illustrated in FIG. **1B**, where a chassis may not include a plastic portion for antenna requirements or other functional reasons, a small portion **106** of the surrounding frame of the chassis **108** that includes the opening **102** may be composed from a plastic material and integrated with the metal portion of the chassis **108**. This small portion **106** of the surrounding frame of the chassis **108** may be made to accommodate the opening **102**, and the small portion **106** may “snap” into place within the remaining metal portion of the surrounding frame of the chassis **108** in order to allow a metal plug to be inserted within the plastic opening **102**, and to reduce the risk of shorting out when the metal plug is inserted.

FIGS. **2A-2C** illustrate partial exterior and interior views of chassis of a device with integrated audio jack housing according to an example implementation.

According to certain implementations, an audio jack housing **202** may be assembled and installed within a computing device **200** to accept insertion of an audio plug

through an opening **204** of the computing device **200**. As described above, a chassis **208** of the computing device **200** may have an inner support surface and outer surrounding frame. The audio jack housing may be mounted on the inner support surface of the chassis **208**. The audio jack housing **202** may include a cylindrical extrusion, or a “snout” **210** which may be configured to align with and abut an interior edge of the opening **204** when the audio jack housing is mounted on the inner support surface of the chassis within the computing device **200** as shown in the interior view of FIG. **2A**.

During assembly, as will be described in FIG. **3** and FIG. **4**, the audio jack housing **202** may be mounted on the inner support structure of the chassis **208** of the computing device **200** and slid into position in a direction toward the opening until the snout **210** abuts the surrounding frame of the chassis **208** and is aligned with the opening **204**. Once the audio jack housing **202** is aligned in position, a screw **214** may be inserted to fasten the audio jack housing **202** in place.

As shown in FIGS. **2B** and **2C**, in a system according to certain implementations, when the audio jack housing **202** is positioned in place on the inner support surface of the chassis **208** within the computing device **200**, the snout **210** of the audio jack housing **202** is configured to concentrically align with and abut an interior edge **205** of the opening **204** of the surrounding frame of the chassis **208**, and the snout **210** does not protrude into past the interior edge **205** of the opening **204**.

In a system according to certain implementations, a portion **207** of the surrounding frame of the chassis **208** including the opening **204** may be composed from a plastic material. The plastic material may prevent shorting out of the computing device **200** when a metal audio plug is inserted into the opening **204**. Thus, the plastic portion **207** enables the audio jack housing to remain interior to the computing device and to align with the opening **204** without protruding into the opening **204**, since the risk of shorting out is reduced due to the plastic portion **207** of the surrounding frame of the chassis **208** where the opening **204** is located.

FIG. **2C** illustrates another external view of the computing device **200** with the audio jack housing **202** positioned in place on the inner support surface of the chassis **208**. As shown, the snout **210** of the audio jack housing **202** is aligned with and abuts an interior edge **205** of the opening **204** of the surrounding frame of the chassis **208**, but does not protrude into the opening **204**. Thus, an inner surface **211** of the opening **204** in the plastic portion of the chassis **208** is visible when the audio jack housing **202** is positioned in place. When an audio plug is inserted into the opening **204**, the metal plug may be in contact with inner surface **211** of the opening **204**.

FIGS. **3A-3B** illustrate an example audio jack housing.

As described above, an audio jack housing **300** may include a snout **310** which may be configured to align with and abut an opening **304** formed in a surrounding frame of a chassis **308** of a computing device. A portion of the surrounding frame and the inner support structure of the chassis **308** where the opening is located may include a plurality of alignment features to facilitate concentric alignment and abutment of the snout **310** with the opening **304** of the chassis **308**.

In an example, the snout **310** may have an angled surface **312** that may be configured to align with the one or more alignment features of the chassis **308** associated with the opening. For example, the alignment features of the chassis

308 may include a coordinating angled surface (partially shown as chamfered surface **315**) on an interior edge of the opening **304** (see e.g., interior edge **205** of FIG. 2C from which the coordinating angled surface can extend), and at least one cylindrical alignment rib **316** formed on the internal surface of the surrounding frame of the chassis **308** near the opening **304**. These alignment features of the chassis are shown and described in more detail in FIG. 4.

As described above, during assembly the audio jack housing **300** is inserted onto the inner support structure of the chassis **308** within an interior portion of a computing device, and the audio jack housing **300** is slid into position in a direction toward the opening until the snout **310** abuts the opening in the chassis **308**. In order to stabilize the audio jack housing **300** after insertion, the audio jack housing **300** may include an extended pin **314** on a bottom side, as shown in FIG. 3A.

As shown in FIG. 3B, the pin **314** may be configured to fit between at least two elongated ribs **318** or protrusions of the chassis **308** as the audio jack housing **300** is slid into place towards the opening **304**, and the pin **314** may prevent the audio jack housing **300** from rotating or tipping in a direction perpendicular to the opening **304**. Additionally, in order to secure the audio jack housing **300** in position on the inner support structure of the chassis **308**, the audio jack housing **300** may include an opening **322** for accepting a fastener such as a screw. The opening **322** for accepting the fastener is shown in FIG. 3A. Once the audio jack housing **300** is in place where it is aligned with and abuts the opening **304** in the chassis **308**, a screw **324**, shown in FIG. 3B, may be inserted through the opening **322** to secure the audio jack housing **300** to the inner support structure of the chassis **308**. The inner support structure of the chassis **308** may include a coordinating opening that aligns with the opening **322** of the audio jack housing **300**, and the coordinating opening may be threaded to accept insertion of the screw **324** to secure the audio jack housing **300** to the chassis **308**.

In further examples, an external portion of the audio jack housing **300** may be constructed from a plastic material, and the audio jack housing **300** may include one or more metal contacts **326**, a portion of which are viewable in FIG. 3B, and which are described in further detail in FIG. 4B.

FIGS. 4A-4B illustrate one or more "alignment features" for aligning an audio jack housing with an opening in a chassis according to an example implementation.

As shown in FIG. 4A, a chassis **408** including an opening **404** may include one or more alignment features configured to align and position an inserted audio jack housing. The external portion of an inserted audio jack housing is shown as a wire frame in FIG. 4A in order to allow visibility of the alignment features of the chassis and spring contacts of the audio jack housing.

In an example, alignment features of the chassis **408** may include one or more angled or chamfered surfaces **412** and one or more alignment ribs **414** as briefly described previously. The chamfered surfaces **412** may be on an interior edge of the opening in the surrounding frame of the chassis, and may be configured to align with a coordinating angled surface (previously illustrated as angled surface **312**) of a snout of the audio jack housing as described in FIG. 3A. During insertion of the audio jack housing, the chamfered surfaces **412** may act as an initial alignment lead-in to initially position the audio jack housing into approximately the desired position where the audio jack housing **400** is concentrically aligned with the opening. For example, the audio jack housing **400** may be slid in a direction towards the opening until the snout of the audio jack housing **400**

comes into contact with and abuts the chamfered surfaces **412** and is prevented from sliding any further. Additionally, one or more alignment ribs **414** protruding from an internal surface of the surrounding frame of chassis **408** near the opening may concentrically position and align the audio jack housing **400** in place as the audio jack housing **400** is slid into position against the chamfered surfaces **412**.

Two cylindrical alignment ribs **414** may protrude from the surrounding frame of the chassis on opposing sides of the opening, and the snout of the audio jack may be configured to fit between the two cylindrical alignment ribs **414** to concentrically align the snout of the audio jack housing with the opening. That is, the cylindrical alignment ribs **414** may partially encapsulate the snout to concentrically align the snout of the audio jack housing with the opening. Although two opposing cylindrical alignment ribs are shown and described, more or fewer ribs may be used.

As shown in FIGS. 4A and 4B, the cylindrical alignment ribs **414** may be separate partial ribs positioned on opposing sides of the opening to encapsulate the snout of the audio jack housing. For example, as shown in FIG. 4B, cylindrical alignment rib **414a** may oppose cylindrical alignment rib **414b**. In other examples, there may be a single contiguous cylindrical alignment rib protruding around the opening, or there may be three or more partial alignment ribs configured to concentrically encapsulate and concentrically align the snout with the opening.

As also shown in FIG. 4B, in some examples, an external portion of the audio jack housing **400** may be constructed from a plastic material, and the audio jack housing **400** may include one or more sheet metal spring contacts **426**, which may be configured to make electrical contact with a metal audio plug when the audio plug is inserted into the opening. The metal contacts **426** may be composed from a sheet metal and may be constructed as spring contacts having some flexibility.

FIGS. 5A-5B illustrate cross sectional views of an audio jack housing in position and aligned with an opening in a chassis according to an example implementation.

FIGS. 5A and 5B show the audio jack housing **500** in position within a computing device where an angled surface **502** of a snout **505** of the audio jack housing **500** abuts a corresponding chamfered surface **504** of an internal surface (e.g., extending from interior edge **205** of FIG. 2C) of the opening **512** of a surrounding frame of a chassis **510** of the computing device. As described above, the chamfered surface **504** of the internal surface of the opening in the chassis **510** may act as an initial "lead-in" to guide the audio jack housing **500** into position where it abuts and is concentrically aligned with the opening **512**. When the audio jack housing **500** is in position on an inner support surface **507** of the chassis **510**, the snout **505** (see also angled surface **312** of snout **310** of FIG. 3A) abuts the opening in the surrounding frame of the chassis **510** and does not protrude into the opening **512** along internal surface **511**. In some implementations, a size (diameter) of the snout **505** of the audio jack housing **500** may be substantially similar to the diameter of the opening **512** so that the edges allow a smooth entry for an audio plug through the opening **512** and snout **505** into the audio jack housing **500**. In some examples, the diameter of the snout **505** may be substantially the same, but not exactly the same, due to tolerances. In some cases, the diameter of the snout **505** may be slightly smaller than the diameter of the opening **512**. An external audio plug is designed to fit tightly within the snout **505** of the audio housing, and the opening **512** of the chassis may be bigger

than the diameter of the snout **505** to ensure the audio plug fits through the opening **512** into the snout **505** of the audio jack housing.

Also shown in FIGS. **5A** and **5B** are one or more spring contacts **526** of the audio jack housing **500**, which may be configured to come into contact with an audio plug when the audio plug is inserted into the opening **512**. Additionally shown in FIGS. **5A** and **5B** is an extrusion pin **514** on a bottom side of the audio jack housing **500**, which may be configured to fit between at least two elongated ribs **518** or protrusions of the inner support surface of the chassis **510** as the audio jack housing **500** is slid into place towards the opening **512** of the chassis **510**. As described previously, the extrusion pin **514** may prevent the audio jack housing **500** from rotating or tipping.

The detailed description provided above in connection with the appended drawings is intended as a description of examples and is not intended to represent the only forms in which the present examples may be constructed or utilized.

It is to be understood that the configurations and/or approaches described herein are exemplary in nature, and that the described implementations and/or examples are not to be considered in a limiting sense, because numerous variations are possible. The specific processes or methods described herein may represent one or more of any number of processing strategies. As such, various operations illustrated and/or described may be performed in the sequence illustrated and/or described, in other sequences, in parallel, or omitted. Likewise, the order of the above-described processes may be changed.

Although the subject matter has been described in language specific to structural features and/or methodological acts, it is to be understood that the subject matter defined in the appended claims is not necessarily limited to the specific features or acts described above. Rather, the specific features and acts described above are presented as example forms of implementing the claims.

What is claimed is:

1. An integrated audio jack housing assembly comprising: a chassis including a surrounding frame and an inner support surface, the chassis having at least a portion thereof comprising plastic and having an opening in the portion of the surrounding frame comprising plastic, wherein an internal surface of the chassis around the opening comprises alignment features; and an audio jack housing abutting the internal surface of the chassis around the opening without protruding into an interior surface of the opening; wherein the alignment features include a chamfered surface extending from an interior edge of the opening facing the audio jack housing.
2. A method of assembling an integrated audio jack housing assembly, the method comprising: inserting an audio jack housing on an inner support surface of a chassis with a snout of the audio jack housing facing an opening in a plastic portion of a surrounding frame of the chassis; sliding the audio jack housing in a direction towards the opening of the surrounding frame of the chassis until the snout contacts an internal surface of the surrounding frame of the chassis around the opening and is aligned between two or more cylindrical alignment ribs protruding from the internal surface of the surrounding frame of the chassis near the opening, wherein the snout does not protrude into the opening; and fastening the audio jack housing to the inner support surface of the chassis.

3. The integrated audio jack housing assembly of claim 1, wherein the audio jack housing has a cylindrical extrusion, wherein the cylindrical extrusion includes an angled surface configured to correspond to the chamfered surface.

4. The integrated audio jack housing assembly of claim 3, wherein the internal surface of the chassis around the opening includes one or more cylindrical alignment ribs extending from at least a portion of the internal surface of the opening, the one or more cylindrical alignment ribs configured to concentrically encapsulate the cylindrical extrusion of the audio jack housing to concentrically align the cylindrical extrusion with the opening.

5. The integrated audio jack housing assembly of claim 3, wherein the audio jack housing includes at least one extrusion pin on a bottom side of the audio jack housing, the extrusion pin configured to fit between at least two elongated protrusions extending from a portion of the inner support surface of the chassis.

6. The integrated audio jack housing assembly of claim 3, wherein a diameter of the cylindrical extrusion is substantially the same as a diameter of the interior surface of the opening.

7. The integrated audio jack housing assembly of claim 1, wherein the audio jack housing includes at least one hole to enable securing the audio jack housing to the inner support surface of the chassis.

8. The integrated audio jack housing assembly of claim 7, wherein the at least one hole of the audio jack housing aligns with at least one hole in the inner support surface of the chassis when the audio jack housing abuts and is concentrically aligned with the opening in the surrounding frame of the chassis.

9. The integrated audio jack housing assembly of claim 1, wherein at least a portion of the audio jack housing comprises a plastic material.

10. The integrated audio jack housing assembly of claim 1, wherein the audio jack housing includes one or more spring contacts.

11. The integrated audio jack housing assembly of claim 10, wherein the one or more spring contacts are configured to make electrical contact with an audio plug when the audio plug is inserted into the opening in the surrounding frame of the chassis.

12. A computing device comprising:

- a chassis including a surrounding frame and an inner support surface, the chassis having at least a portion thereof comprising plastic and having an opening in the portion of the surrounding frame comprising plastic; and
- an audio jack housing abutting an internal surface of the chassis around the opening without protruding into an interior surface of the opening, wherein the audio jack housing has a cylindrical extrusion, and wherein the cylindrical extrusion concentrically aligns with one or more alignment features at an internal surface of the chassis around the opening.

13. The computing device of claim 12, wherein the one or more alignment features comprise:

- a chamfered surface extending from an interior edge of the opening and configured to abut a coordinating angled surface of the cylindrical extrusion of the audio jack housing.

14. The computing device of claim 12, wherein the one or more alignment features comprise:

- one or more cylindrical alignment ribs protruding from at least a portion of the internal surface of the chassis near the opening in the surrounding frame of the chassis, the

one or more cylindrical alignment ribs configured to concentrically encapsulate the cylindrical extrusion of the audio jack housing to concentrically align the cylindrical extrusion with the opening.

15. The computing device of claim 12, wherein a diameter of the cylindrical extrusion is substantially the same as a diameter of the interior surface of the opening.

16. The computing device of claim 12, wherein the audio jack housing includes one or more spring contacts for making electrical contact with a plug inserted into the opening.

17. The computing device of claim 12, wherein the audio jack housing has at least one hole for accepting a fastener, and wherein the at least one hole aligns with at least one hole located on the inner support surface of the chassis when the audio jack housing abuts and is concentrically aligned with the opening in the surrounding frame of the chassis.

18. The method of claim 2, wherein the audio jack housing has at least one hole for accepting a fastener, and wherein the at least one hole aligns with at least one hole located on the inner support surface of the chassis when the audio jack housing abuts and is concentrically aligned with the opening in the surrounding frame of the chassis.

19. The method of claim 2, wherein an angled surface of the snout abuts a corresponding chamfered surface of the internal surface around the opening.

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